A SAWING APPARATUS AND A CONTROL METHOD FOR MANUFACTURING PROCESSES OF SEMICONDUCTOR PACKAGE

ABSTRACT

Disclosed is a sawing apparatus for manufacturing a semiconductor package, capable of simultaneously performing strip loading work and package unloading work during the sawing process to improve productivity of the semiconductor packages. The sawing apparatus includes a chuck table base 200; a chuck table 23 installed on the chuck table base 200 such that the chuck table 23 horizontally moves on the chuck table base 200; two chuck plates 233a and 233b rotatably installed on the chuck table 23 such that a strip S is loaded on upper surfaces of the chuck plates 233a and 233b by turns; a sawing machine 30 for dividing the strip S loaded on the chuck plate into individual packages P by performing a relative movement with respect to the chuck table 23; and a strip/package picker 22 for loading the strip S onto the chuck plates and unloading the packages P from the chuck plates, simultaneously.

Fig. 3